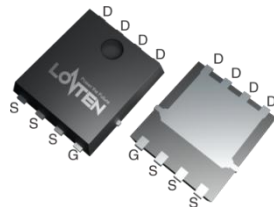
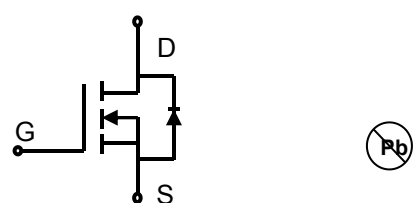


Lonten N-channel 40V, 130A, 1.85mΩ Power MOSFET

Description These N-Channel enhancement mode power field effect transistors are using shielded gate trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.	Product Summary <table> <tr> <td>V_{DS}</td><td>40V</td></tr> <tr> <td>$R_{DS(on),max}@V_{GS}=10V$</td><td>1.85mΩ</td></tr> <tr> <td>I_D</td><td>130A</td></tr> </table>	V_{DS}	40V	$R_{DS(on),max}@V_{GS}=10V$	1.85mΩ	I_D	130A
V_{DS}	40V						
$R_{DS(on),max}@V_{GS}=10V$	1.85mΩ						
I_D	130A						
Features <ul style="list-style-type: none"> ◆ 40V, 130A, $R_{DS(on),max}=1.85m\Omega@V_{GS}=10V$ ◆ Improved dv/dt capability ◆ Fast switching ◆ 100% EAS Guaranteed ◆ Green device available Applications <ul style="list-style-type: none"> ◆ DC-DC Converter ◆ Hard switching and high speed circuit 	Pin Configuration  <p style="text-align: center;">DFN5×6</p>  <p style="text-align: center;">N-Channel MOSFET</p>						

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	40	V
Continuous drain current ($T_C = 25^\circ\text{C}$) ($T_C = 100^\circ\text{C}$)	I_D	130 82	A A
Pulsed drain current ¹⁾	I_{DM}	400	A
Gate-Source voltage	V_{GSS}	± 20	V
Avalanche energy ²⁾	E_{AS}	320	mJ
Power Dissipation	P_D	89	W
Storage Temperature Range	T_{STG}	-55 to +175	$^\circ\text{C}$
Operating Junction Temperature Range	T_J	-55 to +175	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.4	$^\circ\text{C/W}$

Package Marking and Ordering Information

Device	Device Package	Marking
LSGN04R018WE	DFN 5×6	04R018WE

Electrical Characteristics
 $T_J = 25^{\circ}\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0 V, I _D =250uA	40	---	---	V
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	1.0	---	2.2	V
Drain-source leakage current	I _{DSS}	V _{DS} =40 V, V _{GS} =0 V, T _J = 25°C	---	---	1	μA
		V _{DS} =40 V, V _{GS} =0 V, T _J = 150°C	---	---	10	mA
Gate leakage current, Forward	I _{GSSF}	V _{GS} =20 V, V _{DS} =0 V	---	---	100	nA
Gate leakage current, Reverse	I _{GSSR}	V _{GS} =-20 V, V _{DS} =0 V	---	---	-100	nA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} =10 V, I _D =75 A, T _J = 25°C	---	1.3	1.85	mΩ
Dynamic characteristics						
Input capacitance	C _{iss}	V _{DS} = 20 V, V _{GS} = 0 V, f = 1MHz	---	3000	---	pF
Output capacitance	C _{oss}		---	895	---	
Reverse transfer capacitance	C _{rss}		---	37	---	
Turn-on delay time	t _{d(on)}	V _{DD} = 20V, V _{GS} =10V, I _D =75 A	---	13	---	ns
Rise time	t _r		---	3	---	
Turn-off delay time	t _{d(off)}		---	52	---	
Fall time	t _f		---	24	---	
Gate charge characteristics						
Gate to source charge	Q _{gs}	V _{DS} =20 V, I _D =75A, V _{GS} = 10 V	---	8	---	nC
Gate to drain charge	Q _{gd}		---	7	---	
Gate charge total	Q _g		---	40	---	
Drain-Source diode characteristics and Maximum Ratings						
Continuous Source Current	I _s		---	---	130	A
Pulsed Source Current	I _{SM}		---	---	400	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =75A, T _J =25°C	---	---	1.2	V
Reverse Recovery Time	t _{rr}	I _S =50A, di/dt=100A/us,	---	35	---	ns
Reverse Recovery Charge	Q _{rr}	T _J =25°C	---	31	---	nC

Notes:

1: Repetitive Rating: Pulse width limited by maximum junction temperature.

2: $V_{DD}=20\text{V}$, $L=0.5\text{mH}$, Starting $T_J=25^{\circ}\text{C}$.

Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

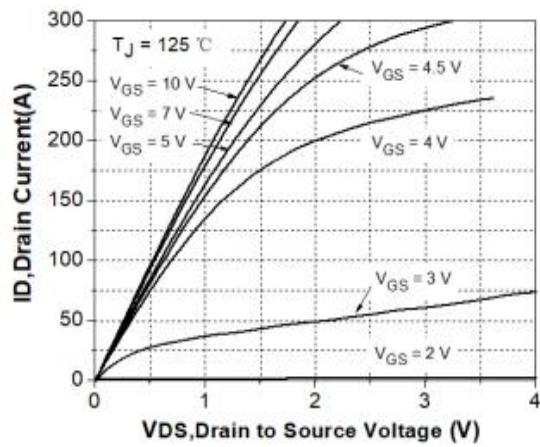


Figure 2. Transfer Characteristics

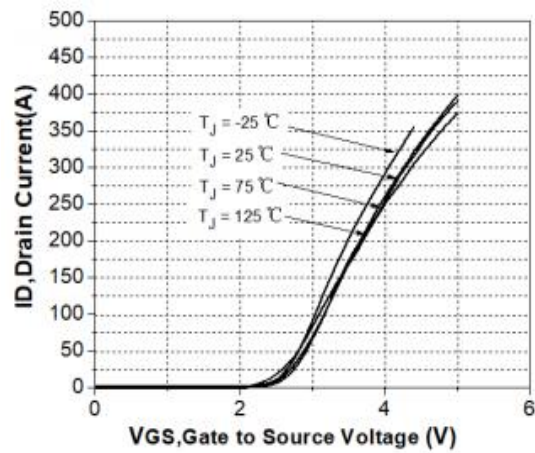


Figure 3. On-Resistance vs. Drain Current

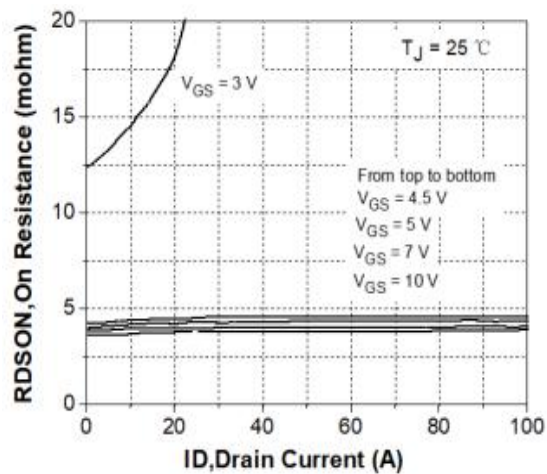


Figure 4. Breakdown Voltage vs. Temperature

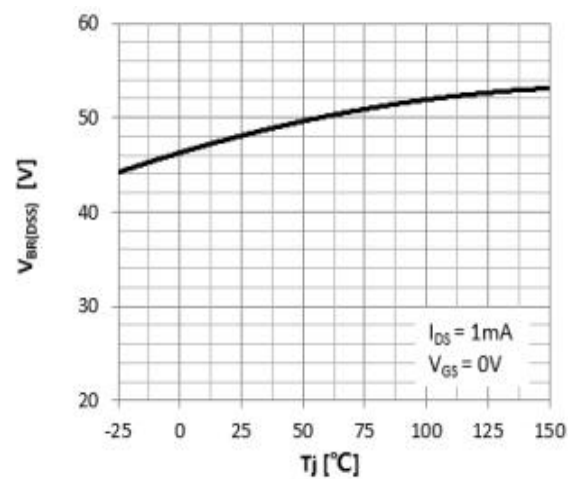


Figure 5. Threshold Voltage vs. Temperature

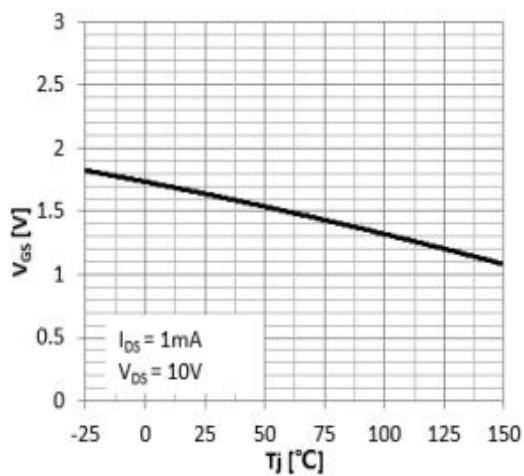


Figure 6. Power Dissipation vs. Temperature

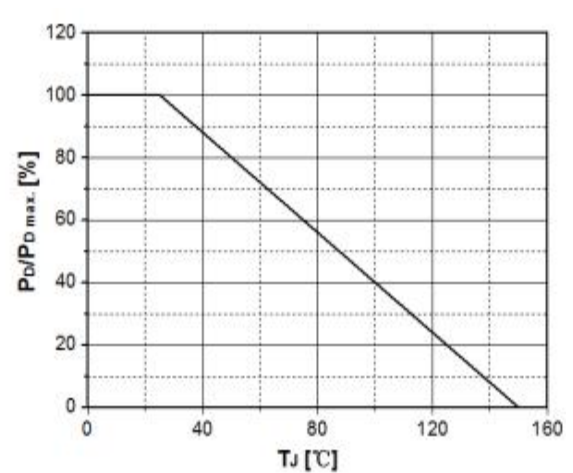


Figure 7.Capacitance Characteristics

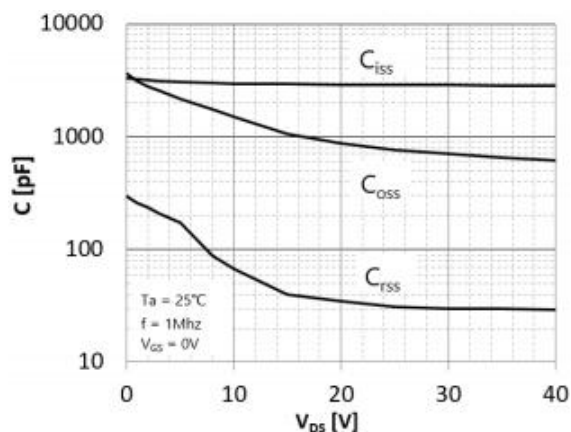


Figure 8.Gate Charge Characteristics

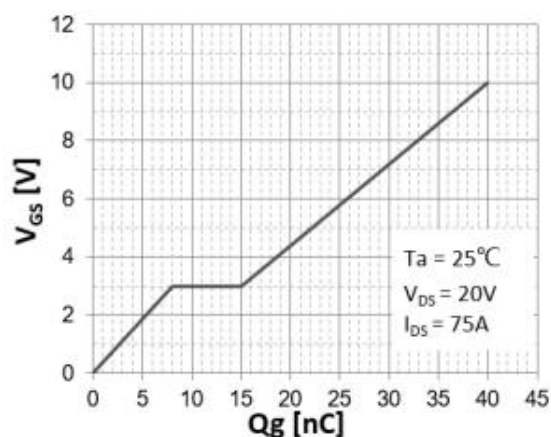


Figure 9: Safe Operating Area

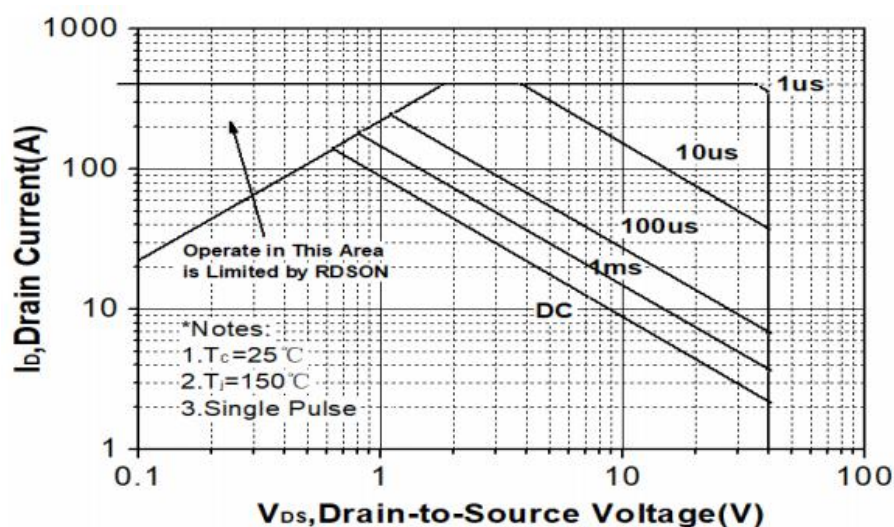
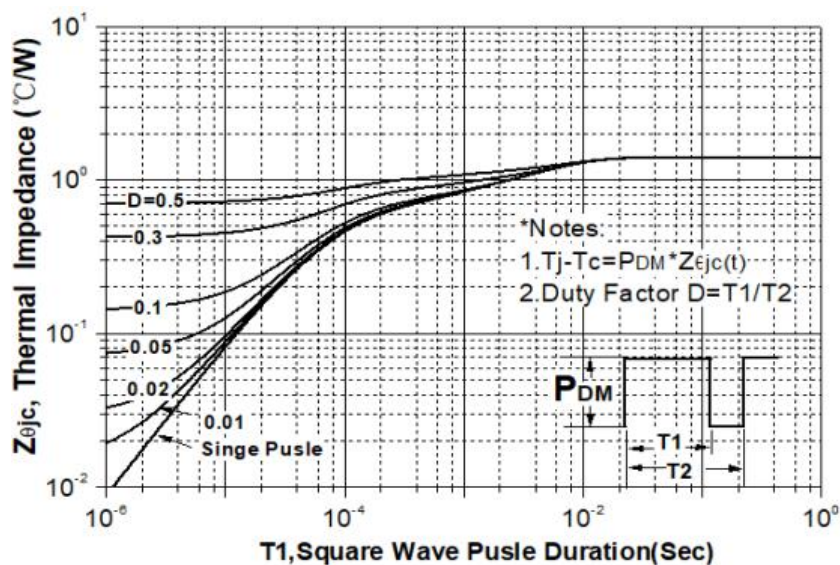
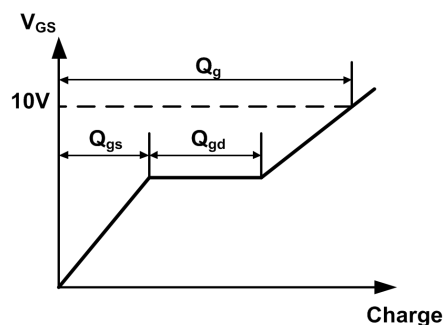
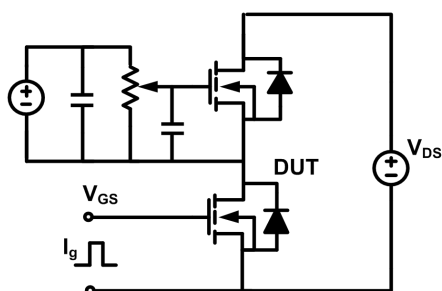


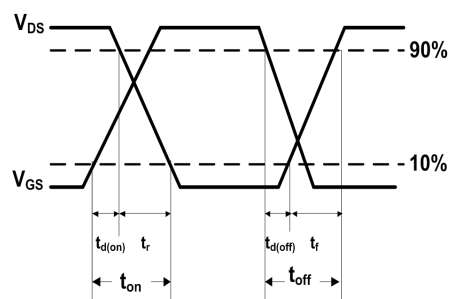
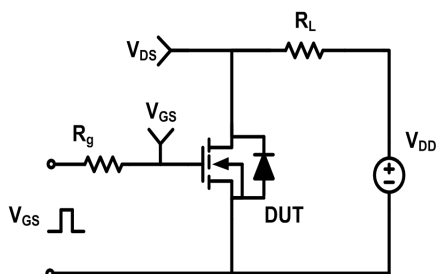
Figure 10. Normalized Maximum Transient Thermal Impedance (R_{thJC})



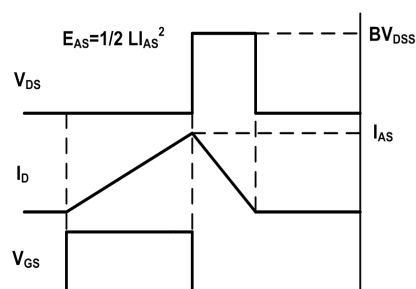
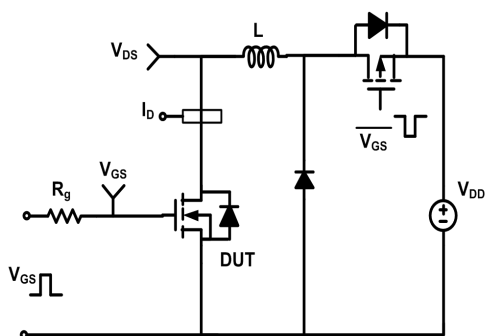
Gate Charge Test Circuit & Waveform



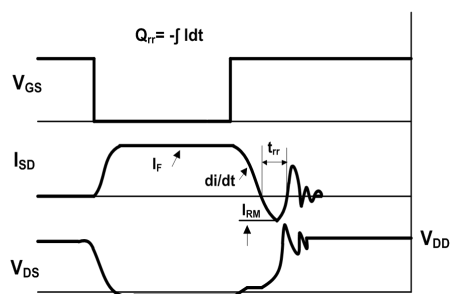
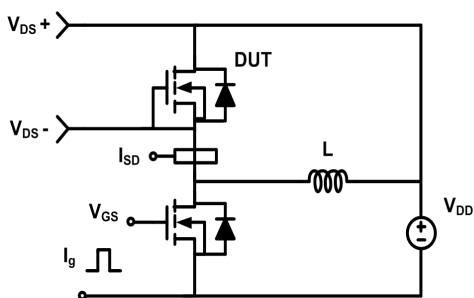
Resistive Switching Test Circuit & Waveform



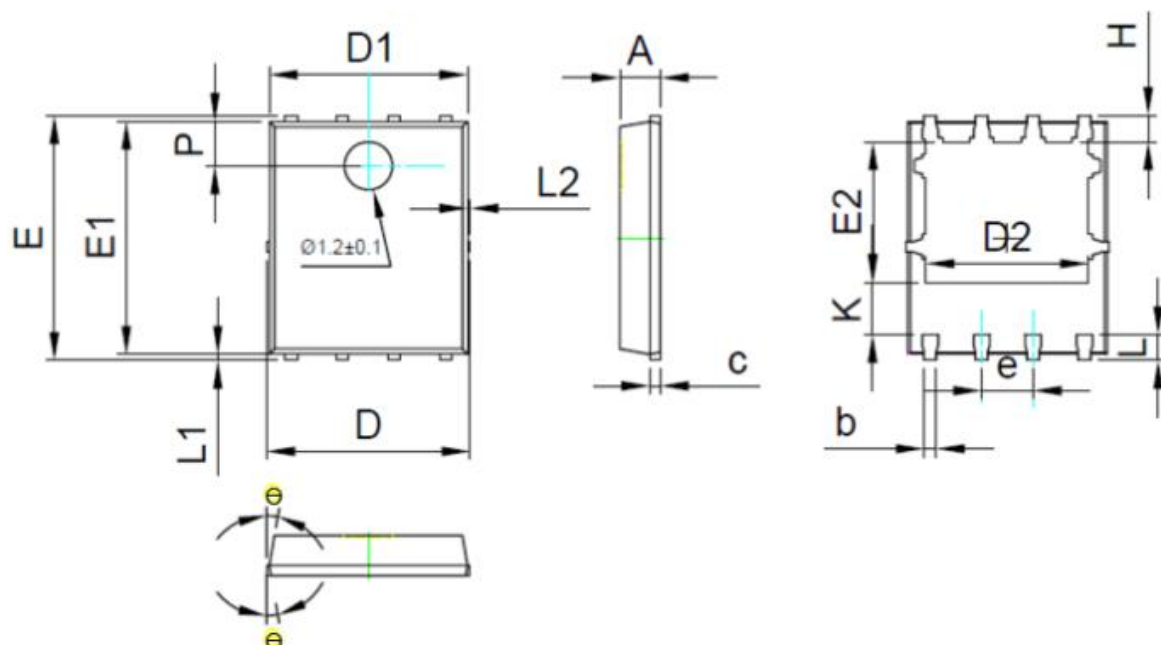
Unclamped Inductive Switching (UIS) Test Circuit & Waveform



Diode Recovery Test Circuit & Waveform



Mechanical Dimensions for DFN 5×6



SYMBOL	MIN	NOM	MAX
A	0.90	1.00	1.10
b	0.35	0.40	0.45
c	0.21	0.25	0.34
D	-	-	5.1
D1	4.85	4.90	4.95
D2	3.96	4.01	4.06
e	1.27 BSC		
E	5.95	6.00	6.05
E1	5.70	5.75	5.80
E2	3.425	3.475	3.525
H	0.60	0.65	0.70
K	1.29	-	-
L	0.60	0.65	0.70
L1	0.05	0.15	0.25
L2	-	-	0.12
θ	8°	10°	12°
P	1.05	1.10	1.15

Version Information

LSGN04R018WE

Revision:2021-11-24 ,Rev 0.1**Disclaimer**

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